

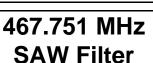
Designed for SDARS Receiver IF Application

- Low Insertion Loss
- 3.8 X 3.8 X 1.2 mm Surface-Mount Case
- Differential Input and Output
- Complies with Directive 2002/95/EC (RoHS)

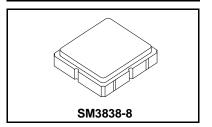


Absolute Maximum Ratings

Rating	Value	Units		
Maximum Incident Power in Passband	+10	dBm		
Max. DC voltage between any 2 terminals	30	VDC		
Storage Temperature Range	-40 to +85	°C		
Suitable for lead-free soldering - Max Soldering Profile	260°C	260°C for 30 s		



SF2024D

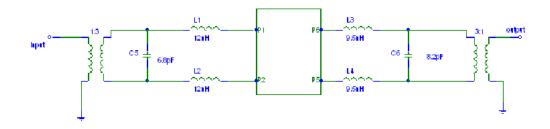


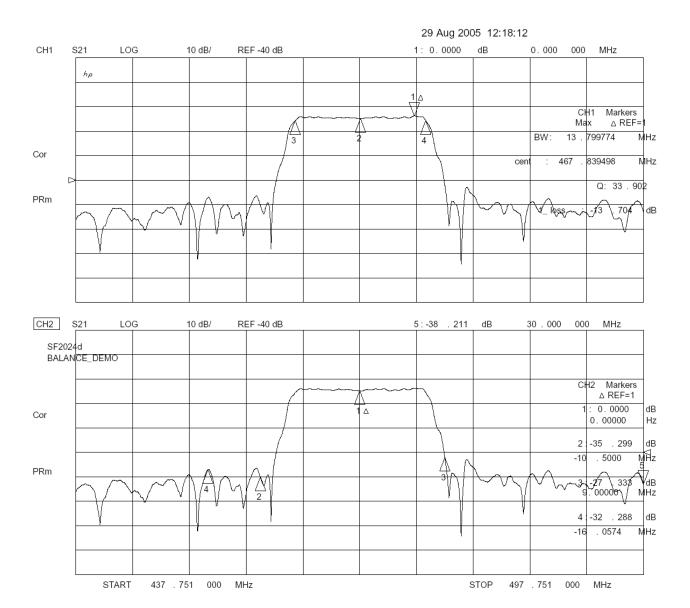
Electrical Characteristics

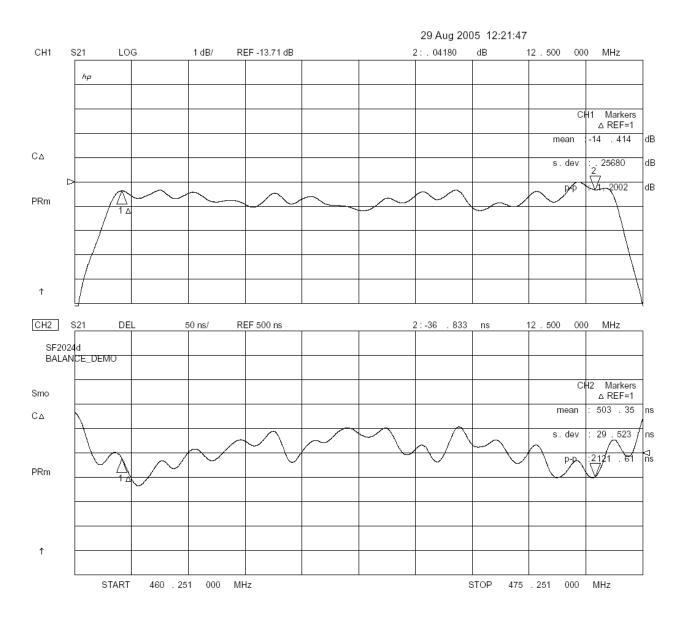
Characteristic		Sym	Notes	Min	Тур	Max	Units
Center Frequency		f _C	1	467.704	467.751	467.798	MHz
Insertion Loss		IL	'		12	13	dB
Amplitude Ripple (p-p)	fc-6.250 to fc-4.3925 MHz					2.0	
	fc-4.3925 to fc-2.535 MHz					2.0	
	fc-2.5350 to fc-0.025 MHz					2.0	dB
	fc+0.025 to fc+2.535 MHz		1, 2			2.0	-
	fc+2.5350 to fc+4.3925 MHz		1, 2			2.0	
	fc+4.3925 to fc+6.250 MHz					2.0	
Pass bandwidth of -2.0dB cente	red at fc				13.0		MHz
Pass bandwidth of -3 dB							IVII IZ
Low Side Attenuation between 4	455.751 to 457.251 MHz (fc-10.5 MHz)			32			
Low Side Attenuation F<455.75	1 MHz			32			dB
High Side Attenuation between	476.751 to 479.751 MHz (fc+9.0 MHz)			20			
High Side Attenuation F<479.75	51 MHz			32			
Temperature Coefficient of frequency	iency					-18	ppm/K
Delay Ripple (p-p)	fc-6.250 to fc-4.3925 MHz		1, 2, 3			100	
	fc-4.3925 to fc-2.535 MHz					100	
	fc-2.5350 to fc-0.025 MHz					120	ns ns
	fc+0.025 to fc+2.535 MHz					120	
	fc+2.5350 to fc+4.3925 MHz					100	
	fc+4.3925 to fc+6.250 MHz					100	
Source Impedance		ZS			150		Ω
Load Impedance		ZL			150		Ω
Case Style			6	SM3838-8 3.8 x 3.8 mm Nominal Footprir		otprint	
Lid Symbolization (YY=year, W\	Lid Symbolization (YY=year, WW=week, S=shift) See note 4		O	580 YWWS			

CAUTION: Electrostatic Sensitive Device. Observe precautions for handling. Notes:

- Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network ana-
- lyzer.
 Unless noted otherwise, all frequency specifications are referenced to the 2. nominal center frequency, fc.
- Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
- The design, manufacturing process, and specifications of this filter are subject to change.
 Tape and Reel Standard Per ANSI / EIA 481.
- 6.
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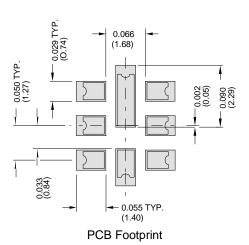




SM3838-8 Case

8-Terminal Ceramic Surface-Mount Case 3.8 X 3.8 mm Nominal Footprint

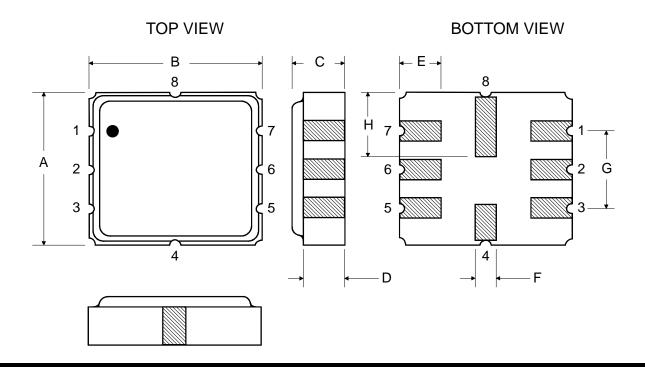




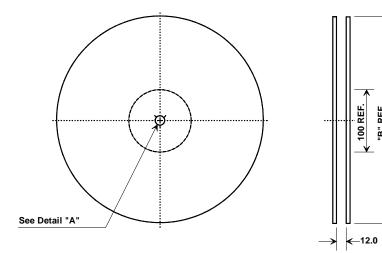
Case Dimensions							
Dimension	mm			Inches			
Dilliension	Min	Nom	Max	Min	Nom	Max	
Α	3.6	3.8	4.0	0.142	0.150	0.157	
В	3.6	3.8	4.0	0.142	0.150	0.157	
С	1.05	1.20	1.35	0.041	0.047	0.053	
D	0.95	1.10	1.25	0.037	0.043	0.049	
E	0.90	1.00	1.10	0.035	0.040	0.043	
F	0.50	0.60	0.70	0.020	0.024	0.028	
G	2.39	2.54	2.69	0.090	0.100	0.110	
Н	1.40	1.75	2.05	0.055	0.069	0.080	

Electrical Connections			
	Connection	Terminals	
Port 1	Differential Input	1, 2	
Port 2	Differential Output	5, 6	
	Ground	All Others	
Single Ended Operation		Return is Ground	
Differential Operation		Return is Hot	
Dot Indicates Pin 1			

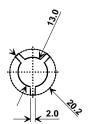
Materials					
Solder Pad Ter- mination	Au plating 30 - 60 ulnches (76.2-152 uM) over 80-200 ulnches (203-508 uM) Ni.				
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 ulnches Thick				
Body	Al ₂ O ₃ Ceramic				
Pb Free					



Tape and Reel Specifications



"B " Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions				
Ao	4.25 mm			
Во	4.25 mm			
Ко	1.30 mm			
Pitch	8.0 mm			
W	12.0 mm			

